



TITLE: THICK SOLDER MASK FOR CONFINING ENCAPSULANT
MATERIAL OVER SELECTED LOCATIONS OF A SUBSTRATE AND
ASSEMBLIES INCLUDING THE SOLDER MASK

Inventor: Grigg et al.
Docket No.: 2269-5216.1US

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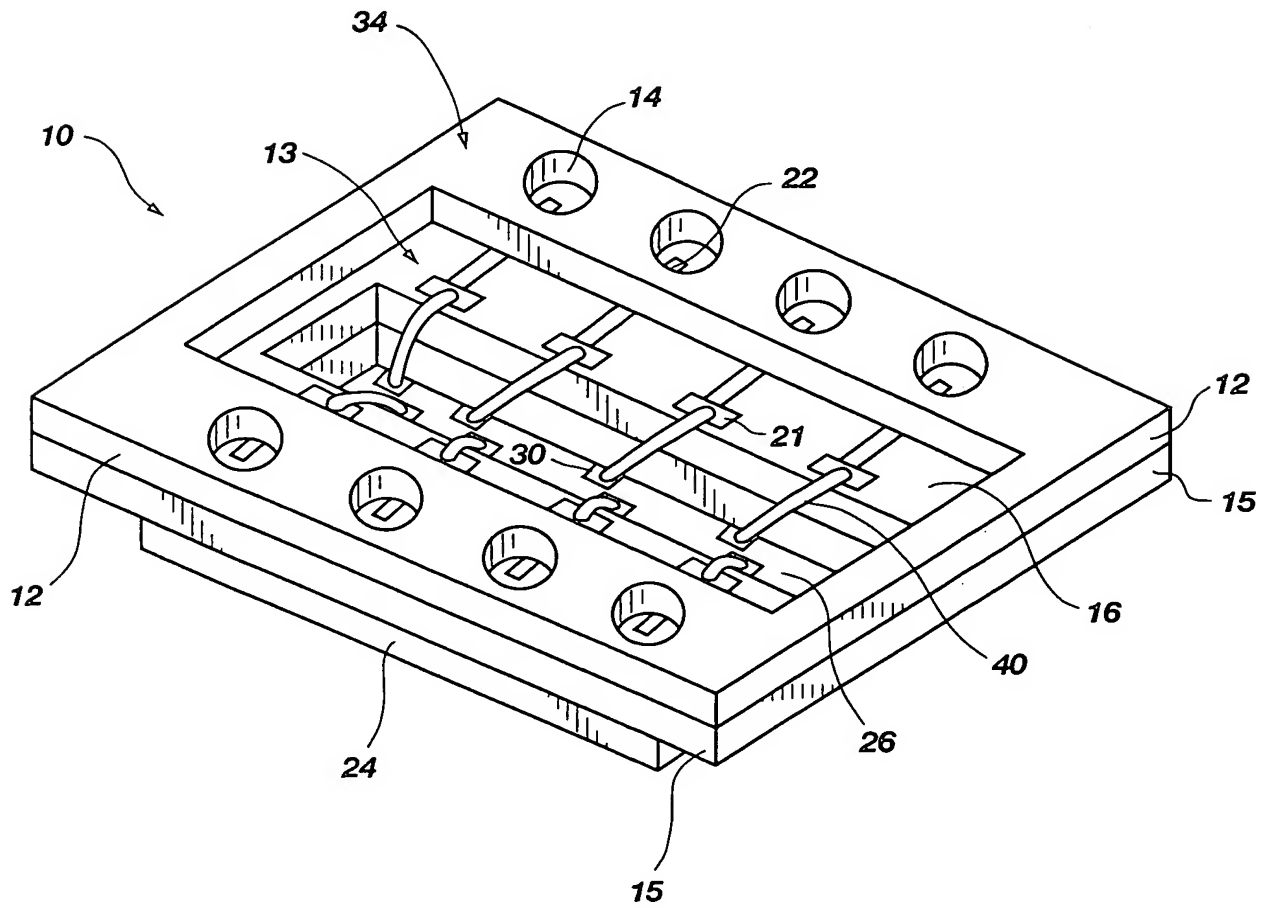


Fig. 2

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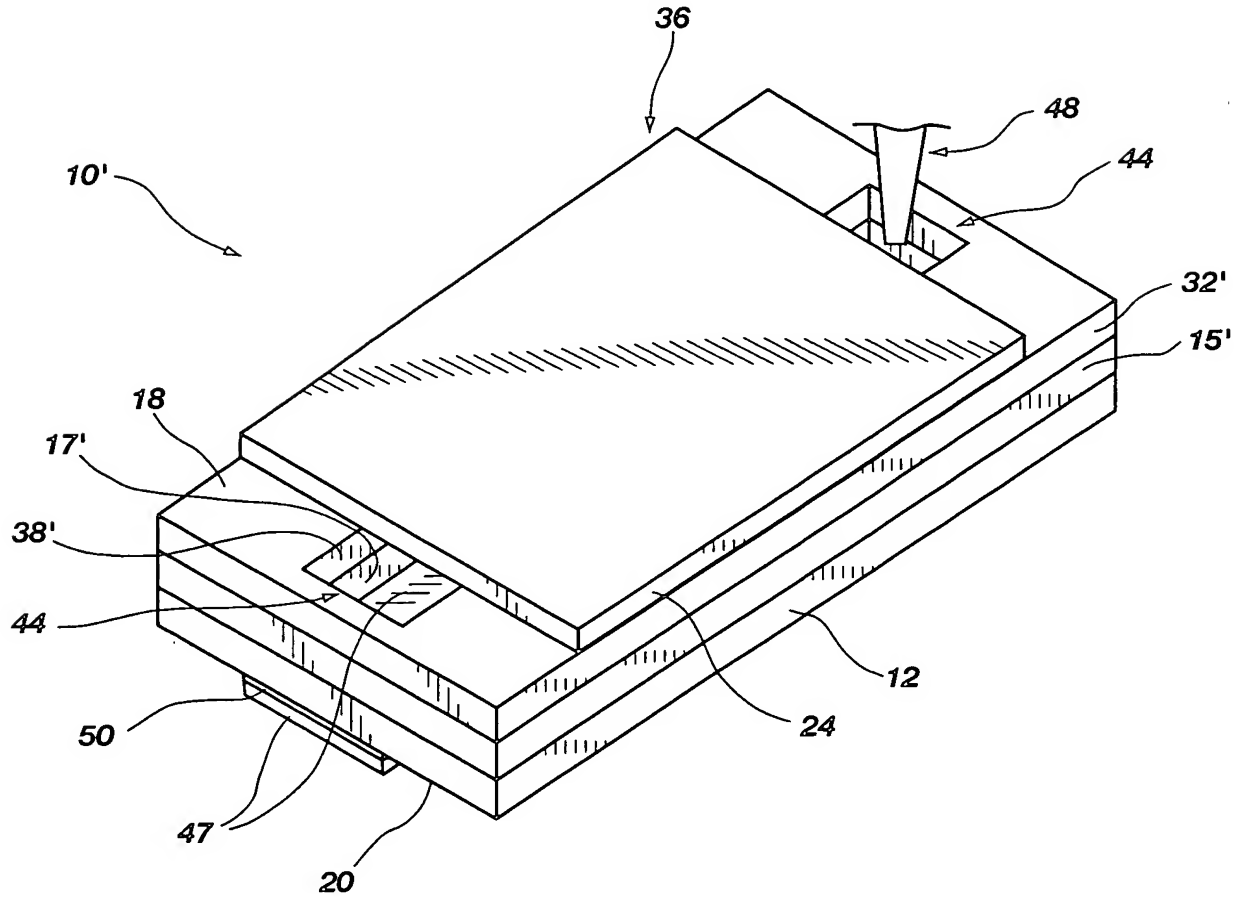


Fig. 3

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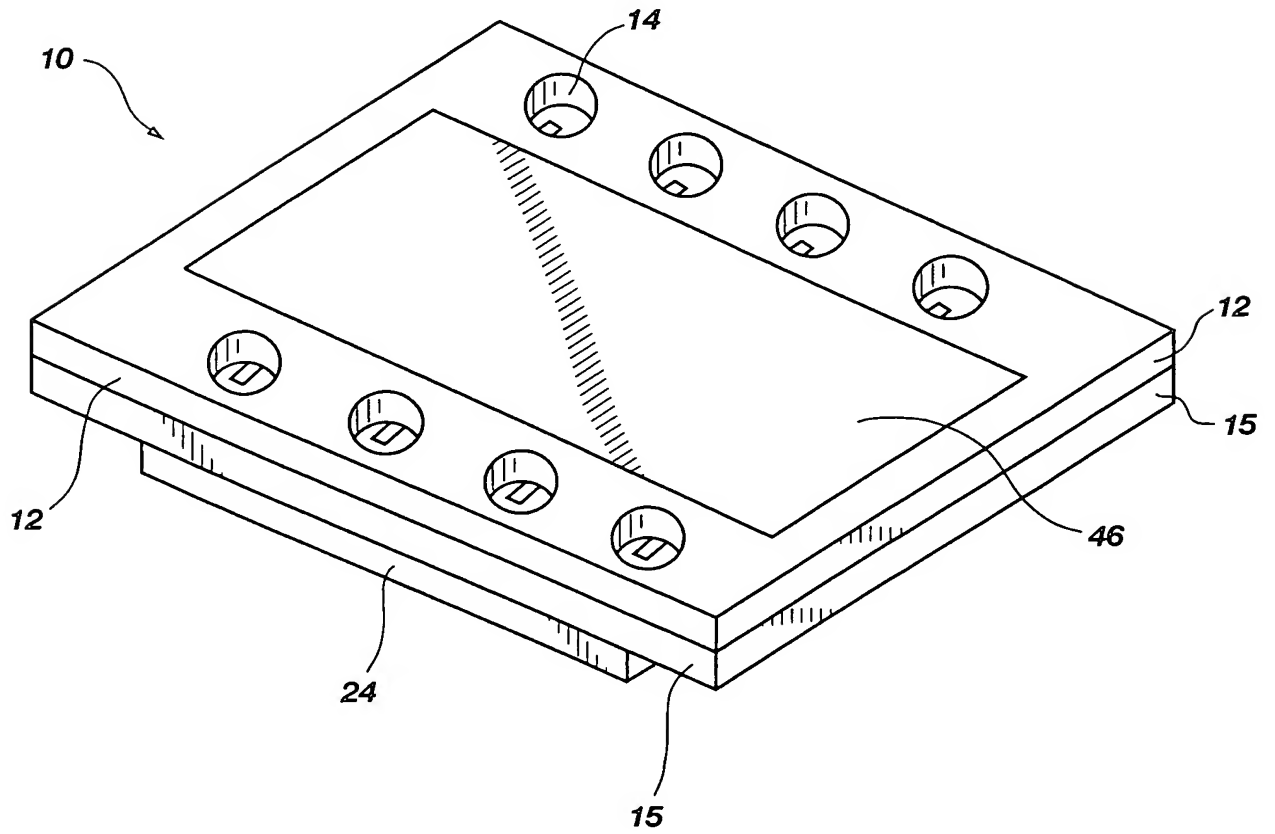


Fig. 4